TOSHIBA

TOSHIBA Field Effect Transistor Silicon N-Channel MOS Type (*π*-MOSVI)

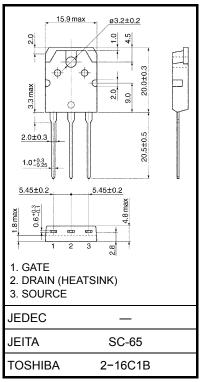
# 2SK3905

#### Switching Regulator Applications

- Low drain-source ON resistance:  $RDS(ON) = 0.25 \Omega$  (typ.)
- High forward transfer admittance:  $|Y_{fs}| = 8.2 \text{ S}$  (typ.)
- Low leakage current:  $I_{DSS} = 100 \ \mu A \ (max) \ (V_{DS} = 500 \ V)$
- Enhancement model:  $V_{th} = 2.0 \sim 4.0 \text{ V} (V_{DS} = 10 \text{ V}, \text{ID} = 1 \text{ mA})$

#### Absolute Maximum Ratings (Ta = 25°C)

Characteristic		Symbol	Rating	Unit	
Drain-source voltage		V <sub>DSS</sub>	500	V	
Drain-gate voltage ( $R_{GS} = 20 \text{ k}\Omega$ )		V <sub>DGR</sub>	500	V	
Gate-source voltage		V <sub>GSS</sub>	±30	V	
Drain current	DC (Note 1)	۱ <sub>D</sub>	17	А	
	Pulse (Note 1)	I <sub>DP</sub>	68	~	
Drain power dissipat	ion (Tc = 25°C)	PD	150	W	
Single pulse avalanche energy (Note 2)		E <sub>AS</sub>	816	mJ	
Avalanche current		I <sub>AR</sub>	17	А	
Repetitive avalanche energy (Note 3)		E <sub>AR</sub>	15	mJ	
Channel temperature	9	T <sub>ch</sub>	150	°C	
Storage temperature range		T <sub>stg</sub>	-55~150	°C	



Weight: 4.6 g (typ.)

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc.).

#### **Thermal Characteristics**

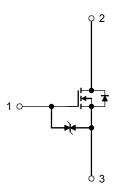
Characteristic	Symbol	Max	Unit	
Thermal resistance, channel to case	R <sub>th (ch-c)</sub>	0.833	°C/W	
Thermal resistance, channel to ambient	R <sub>th (ch-a)</sub>	50	°C/W	

Note 1: Ensure that the channel temperature does not exceed 150°C during use of the device.

Note 2:  $V_{DD} = 90 \text{ V}, \text{ T}_{ch} = 25^{\circ}\text{C}, \text{ L} = 4.8 \text{ mH}, \text{ R}_{G} = 25 \Omega, \text{ I}_{AR} = 17 \text{ A}$ 

Note 3: Repetitive rating: pulse width limited by max junction temperature

This transistor is an electrostatic-sensitive device. Handle with care.



Unit: mm

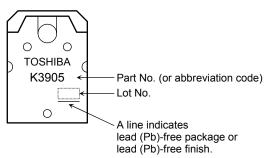
**Electrical Characteristics (Ta = 25°C)** 

Char	acteristic	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cur	rent	I <sub>GSS</sub>	$V_{GS}=\pm 25~V,~V_{DS}=0~V$			±10	μA
Drain-source brea	akdown voltage	V (BR) GSS	$I_G=\pm 10~\mu\text{A},~V_{DS}=0~\text{V}$	±30	_	_	V
Drain cutoff curre	ent	I <sub>DSS</sub>	$V_{DS} = 500 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$	_		100	μA
Drain-source brea	akdown voltage	V (BR) DSS	$I_D=10\ mA,\ V_{GS}=0\ V$	500			V
Gate threshold vo	oltage	V <sub>th</sub>	$V_{DS} = 10 \text{ V}, \text{ I}_{D} = 1 \text{ mA}$	2.0	_	4.0	V
Drain-source ON	resistance	R <sub>DS (ON)</sub>	$V_{GS} = 10 \ V, \ I_D = 8.5 \ A$	_	0.25	0.31	Ω
Forward transfer	admittance	Y <sub>fs</sub>	$V_{DS} = 10 \ V, \ I_D = 8.5 \ A$	2.3	8.2	_	S
Input capacitance		C <sub>iss</sub>		_	3100	_	pF
Reverse transfer capacitance		C <sub>rss</sub>	$V_{DS} = 25 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ f} = 1 \text{ MHz}$	_	20	_	
Output capacitance		C <sub>oss</sub>		_	270		
Switching time	Rise time	tr	$V_{GS}^{10 \text{ V}} \downarrow I_D = 8.5 \text{ A} \\ 0 \text{ V} \downarrow I_D = 8.5 \text{ A} \\ 0 \text{ V} \downarrow I_D = 8.5 \text{ A} \\ 0 \text{ V} \downarrow I_D = 8.5 \text{ A} \\ 0 \text{ V} \downarrow I_D = 24 \Omega \\ 0 \text{ V}_{DD} \approx 200 \text{ V} \\ 0 \text{ Uty} \leq 1\%, t_W = 10 \ \mu\text{s}$		70		
	Turn-on time	t <sub>on</sub>			130		
	Fall time	tf			70		ns
	Turn-off time	t <sub>off</sub>		_	280	_	
Total gate charge (gate-source plus gate-drain)		Qg	$V_{DD}\simeq 400$ V, $V_{GS}=10$ V, $I_{D}=17$ A		62		nC
Gate-source charge		Q <sub>gs</sub>		_	40	_	
Gate-drain ("Miller") charge		Q <sub>gd</sub>			22		

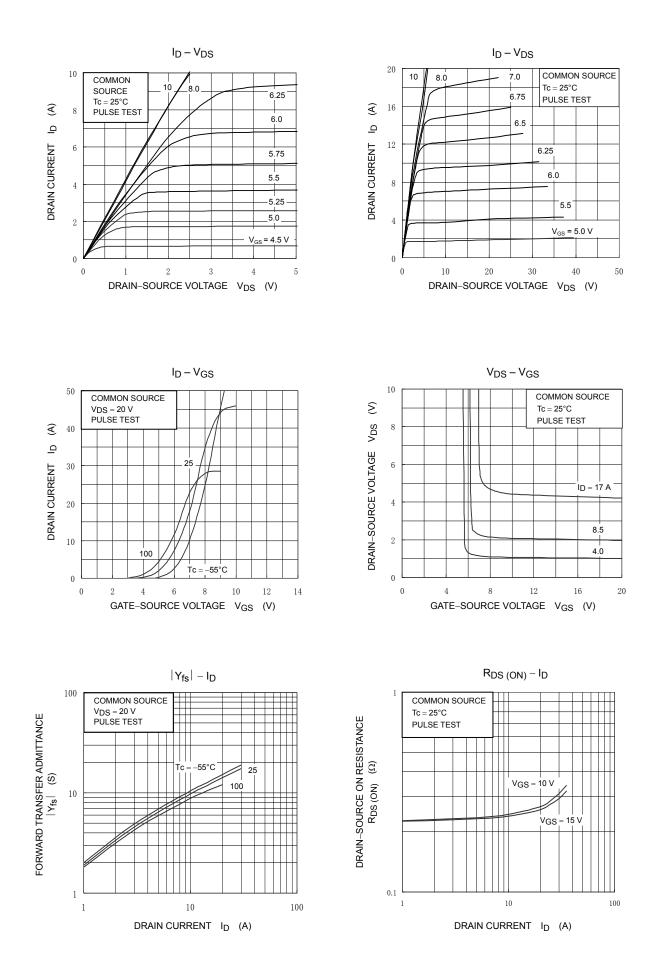
## Source-Drain Ratings and Characteristics (Ta = 25°C)

Characteristic	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I <sub>DR</sub>	—		_	17	А
Pulse drain reverse current (Note 1)	I <sub>DRP</sub>	_	_	_	68	А
Forward voltage (diode)	V <sub>DSF</sub>	$I_{DR} = 17 \text{ A}, V_{GS} = 0 \text{ V}$	_	_	-1.7	V
Reverse recovery time	t <sub>rr</sub>	$I_{DR} = 17 \text{ A}, V_{GS} = 0 \text{ V},$	_	1300	_	μs
Reverse recovery charge	Q <sub>rr</sub>	dI <sub>DR</sub> /dt = 100 A/μs		18		μC

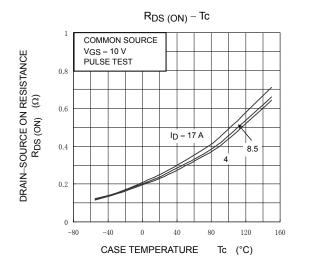
## Marking

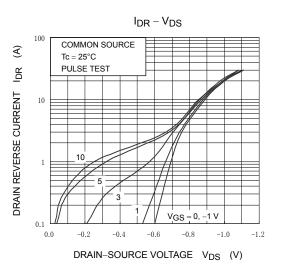


# **TOSHIBA**

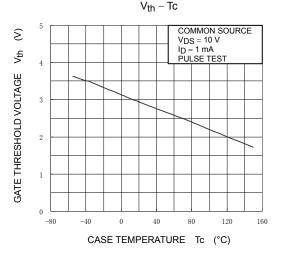


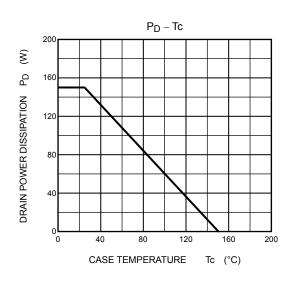
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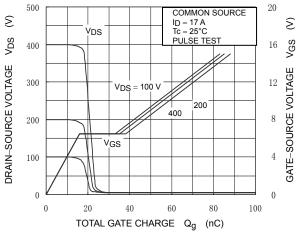


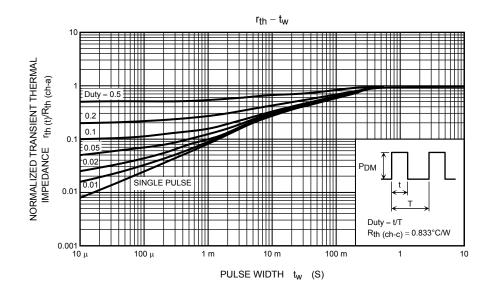
CAPACITANCE - VDS 10000 Ciss (PF) 1000 ပ CAPACITANCE 100 COMMON SOURCE rss VGS = 0 Vf = 1 MHz  $Tc = 25^{\circ}C$ 10 0.1 10 100 DRAIN-SOURCE VOLTAGE VDS (V)





DYNAMIC INPUT/OUTPUT CHARACTERISTICS





SAFE OPERATING AREA 100 ID max (PULSE) \* E 10 DRAIN CURRENT ID ID max (CONTINUOUS) DC 1  $Tc = 25^{\circ}C$ 0.1 SINGLE NONPETITIVE PULSE  $Tc = 25^{\circ}C$ Curves must be derated linearly with V<sub>DSS</sub> max increase in temperature.

10

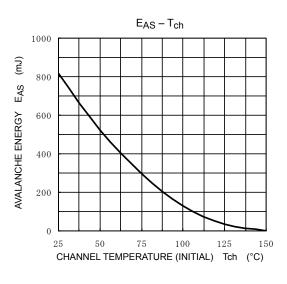
DRAIN-SOURCE VOLTAGE VDS (V)

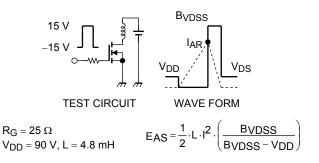
100

1000

0.01

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